

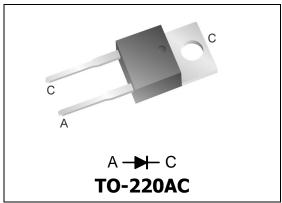
Power integrations\*\*

600 V, 15 A X-Series PFC Diode

## **Product Summary**

$I_{F(AVG)}$	15	Α
$V_{RRM}$	600	V
Q <sub>RR</sub> (Typ at 125 °C)	120	nC
I <sub>RRM</sub> (Typ at 125 °C)	4.6	Α
Softness t <sub>b</sub> /t <sub>a</sub> (Typ at 125 °C)	0.45	

## **Pin Assignment**



**RoHS Compliant** 

Package uses Lead-free plating and Green mold compound. Halogen free per IEC 61249-2-21.

# **General Description**

This device has the lowest  $Q_{RR}$  of any 600 V Silicon diode. Its recovery characteristics increase efficiency, reduce EMI and eliminate snubbers.

## **Applications**

- Power Factor Correction (PFC) boost diode
- · Motor drive circuits
- DC-AC inverters

### **Features**

- Low Q<sub>RR</sub>, low I<sub>RRM</sub>, low t<sub>RR</sub>
- High dI<sub>F</sub>/dt capable (1000 A/µs)
- Soft recovery

### **Benefits**

- · Increases efficiency
  - Eliminates need for snubber circuits
  - Reduces EMI filter component size & count
- Enables extremely fast switching

# **Absolute Maximum Ratings**

Absolute maximum ratings are the values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Symbol	Parameter	Conditions	Rating	Units
$V_{RRM}$	Peak repetitive reverse voltage		600	V
I <sub>F(AVG)</sub>	Average forward current	$T_{\rm J} = 150  {\rm ^{\circ}C},  T_{\rm C} = 101  {\rm ^{\circ}C}$	15	Α
$I_{FSM}$	Non-repetitive peak surge current	60 Hz, 1/2 cycle	95	Α
$I_{FSM}$	Non-repetitive peak surge current	$1/_{2}$ cycle of t=28 $\mu$ s Sinusoid, $T_{C}$ =25 °C	350	Α
$T_{J(MAX)}$	Maximum junction temperature		150	°C
$T_{STG}$	Storage temperature		-55 to 150	°C
	Lead soldering temperature	Leads at 1.6 mm from case, 10 sec	300	°C
$P_D$	Power dissipation	T <sub>C</sub> = 25 °C	96	W

### **Thermal Resistance**

Symbol	Resistance from:	Conditions	Rating	Units
$R_{\theta JA}$	Junction to ambient	TO-220	62	°C/W
$R_{\theta JC}$	Junction to case	TO-220	1.3	°C/W

www.power.com June 2015

### LXA15T600

# Electrical Specifications at $T_J = 25$ °C (unless otherwise specified)

Symbol	Parameter	Conditions		Min	Тур	Max	Units
DC Chara	DC Characteristics						
т	Reverse current	$V_R = 600 \text{ V}, T_J = 25$	°C	-	-	250	μΑ
$I_R$	Reverse current	$V_R = 600 \text{ V}, T_J = 125$	V <sub>R</sub> = 600 V, T <sub>J</sub> = 125 °C		1.7	-	mA
V <sub>F</sub>	Forward voltage	I <sub>F</sub> = 15 A, T <sub>J</sub> = 25 °C		-	2.5	3.1	V
VF	Forward voitage	$I_F = 15 \text{ A}, T_J = 150 \text{ G}$	,C	-	2.2	-	V
$C_{J}$	Junction capacitance	$V_R = 10 \text{ V}, 1 \text{ MHz}$		-	71	-	pF
Dynamic Characteristics							
+	Reverse recovery time	dI/dt =200 A/μs	T₁=25 °C	-	25	-	ns
t <sub>RR</sub>	Reverse recovery time	$V_R$ =400 V, $I_F$ =15 A	T <sub>J</sub> =125 °C	-	39	-	ns
	Daylaraa raaayan aharaa	dI/dt =200 A/μs	T₁=25 °C	-	43	67	nC
$Q_{RR}$	Reverse recovery charge	$V_R = 400 \text{ V}, I_F = 15 \text{ A}$	T <sub>J</sub> =125 °C	-	120	-	nC
т	Maximum reverse	dI/dt =200 A/μs	T <sub>J</sub> =25 °C	-	2.7	3.6	Α
$I_{RRM}$	recovery current	V <sub>R</sub> =400 V, I <sub>F</sub> =15 A	T <sub>J</sub> =125 °C	-	4.6	-	Α
	Softness factor = $\frac{t_b}{t_b}$	dI/dt =200 A/μs	T <sub>J</sub> =25 °C	-	0.7	-	
	$V_R = 400 \text{ V}, I_F = 15 \text{ A}$	T <sub>J</sub> =125 °C	-	0.45	-		

**Note to component engineers**: X-Series diodes employ Schottky technologies in their design and construction. Therefore, Component Engineers should plan their test setups to be similar to those for traditional Schottky test setups. (For additional details, see Application Note AN-300.)

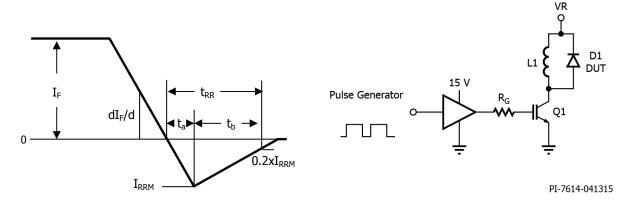
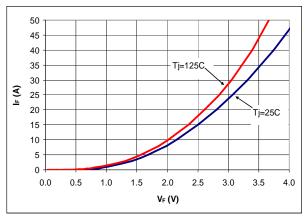


Figure 1. Reverse Recovery Definitions

Figure 2. Reverse Recovery Test Circuit

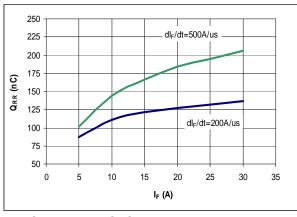
# Electrical Specifications at $T_J = 25$ °C (unless otherwise specified)



250 225 200 175 150 125 0 0 20 40 60 80 100 120 140 160 180 V<sub>R</sub> (V)

Figure 3. Typical I<sub>F</sub> vs V<sub>F</sub>

Figure 4. Typical  $C_j$  vs  $V_R$ 



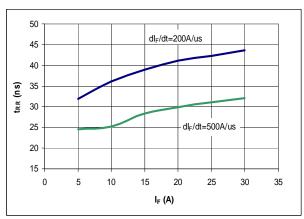
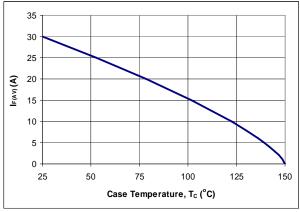


Figure 5. Typical  $Q_{RR}$  vs  $I_F$  at  $T_J$  = 125 °C

Figure 6. Typical  $t_{RR}$  vs  $I_F$  at  $T_J = 125$  °C



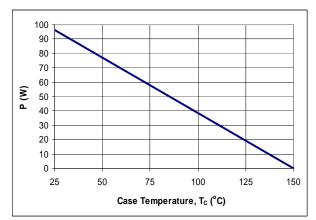


Figure 7. DC Current Derating Curve

Figure 8. Power Derating Curve

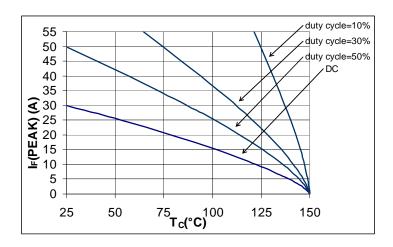
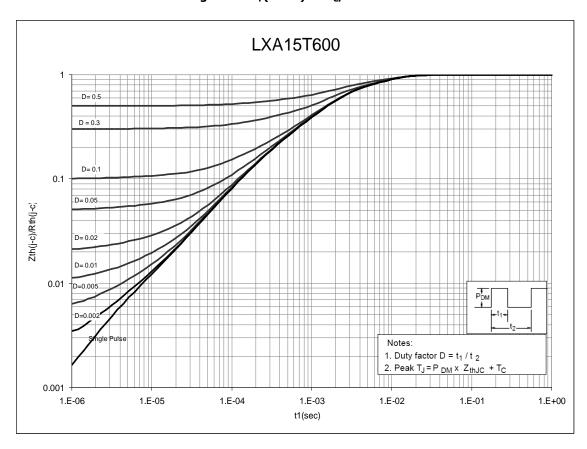


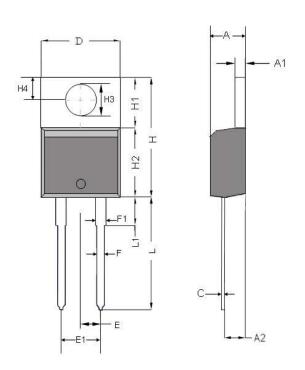
Figure 9.  $I_F(PEAK)$  vs  $T_{C_f}$  f=70 kHz



**Figure 10. Normalized Maximum Transient Thermal Impedance** 



# **Dimensional Outline Drawings**



	Millimeters		
Dim	MIN MAX		
A	4.32	4.70	
A1	1.14	1.40	
A2	2.03	2.79	
С	0.34	0.610	
D	9.65	10.67	
E	2.49	2.59	
E1	4.98	5.18	
F	0.508	1.016	
F1	1.14	1.78	
Н	14.71	16.51	
H1	5.84	6.55	
H2	8.51	9.25	
Н3	3.53	3.96	
H4	2.54	3.05	
L	12.70	14.22	
L1	-	6.35	

Mechanical Mounting Method	Maximum Torque / Pressure specification
Screw through hole in package tab	1 Newton Meter (nm) or 8.8 inch-pounds (lb-in)
Clamp against package body	12.3 kilogram-force per square centimeter (kgf/cm²) or 175 lbf/in²

**Soldering time and temperature:** This product has been designed for use with high-temperature, lead-free solder. The component leads can be subjected to a maximum temperature of 300 °C, for up to 10 seconds. See Application Note AN-303, for more details.

## **Ordering Information**

Part Number	Package	Packing		
LXA15T600	TO-220AC 50 units/tube			

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# LXA15T600

Revision	Notes	Date
1.0	Released by Qspeed	08/09
1.1	Converted to Power Integrations Document	01/11
1.1	Stop Point of t <sub>RR</sub> error corrected due to typo in Figure 1	11/13
1.2	Updated with new Brand Style.	06/15



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